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Vishay Siliconix

Automotive N-Channel 60 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY	
V _{DS} (V)	60
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0125
$R_{DS(on)}$ (Ω) at $V_{GS} = 4.5 \text{ V}$	0.0160
I _D (A)	30
Configuration	Single

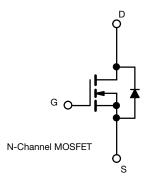
FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % Rq and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





HALOGEN FREE



ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJA60EP (for detailed order number please see www.vishay.com/doc?79771)

ABSOLUTE MAXIMUM RATINGS	G (T _C = 25 °C, unles	ss otherwise noted)			
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V_{DS}	60	V	
Gate-source voltage		V_{GS}	± 20	V	
Continuous drain current	T _C = 25 °C ^a	1	30		
Continuous drain current	T _C = 125 °C	l _D	24.6		
Continuous source current (diode conduction)	a	I _S	30	А	
Pulsed drain current ^b		I _{DM}	84		
Single pulse avalanche current L = 0.1 mH		I _{AS}	23		
Single pulse avalanche energy	L = 0.1 IIII	E _{AS}	26	mJ	
Maximum power dissipation ^b	T _C = 25 °C	P _D	45	W	
waxiinum power dissipation -	$T_C = 125 ^{\circ}C$	VV			
Operating junction and storage temperature ra	ange	T _J , T _{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature	re) ^{d, e}		260	C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount c	R_{thJA}	70	°C/W
Junction-to-case (drain)		R_{thJC}	3.3	G/ VV

Notes

- a. Package limited
- b. Pulse test; pulse width $\leq 300 \,\mu\text{s}$, duty cycle $\leq 2 \,\%$
- d. When mounted on 1" square PCB (FR4 material)
 d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



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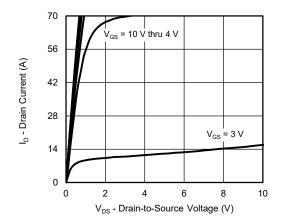
PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS}	= 0, I _D = 250 μA	60	-	-	V
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$		1.5	2.0	2.5	V
Gate-source leakage	I _{GSS}	V _{DS} =	$0 \text{ V}, \text{ V}_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
		V _{GS} = 0 V	V _{DS} = 60 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = 60 V, T _J = 125 °C	=	-	50	μΑ
		V _{GS} = 0 V	V _{DS} = 60 V, T _J = 175 °C	-	-	150	1
On-state drain current a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	30	-	-	Α
		V _{GS} = 10 V	I _D = 8 A	=	0.0101	0.0125	
Drain aguras an atata registance 3	D	V _{GS} = 4.5 V	I _D = 6 A	-	0.0131	0.0160	
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 8 A, T _J = 125 °C	-	-	0.0202	Ω
		V _{GS} = 10 V	I _D = 8 A, T _J = 175 °C	-	-	0.0249	
Forward transconductance b	9fs	V _{DS}	= 15 V, I _D = 8 A	-	46	-	S
Dynamic ^b		•					
Input capacitance	C _{iss}			=	1195	1600	
Output capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 25 V, f = 1 MHz	-	506	660	pF
Reverse transfer capacitance	C_{rss}			=	31	45	
Total gate charge ^c	Qg			=	18	30	
Gate-source charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 30 \text{ V}, I_D = 4 \text{ A}$	-	3.4	-	nC
Gate-drain charge ^c	Q _{gd}			25 V, f = 1 MHz	-		
Gate resistance	R _g		f = 1 MHz	0.2	0.47	0.8	Ω
Turn-on delay time ^c	t _{d(on)}			-	9	15	
Rise time ^c	t _r	$V_{DD} = 30 \text{ V}, R_{L} = 7.5 \Omega$		-	5	10	
Turn-off delay time ^c	t _{d(off)}	$I_D \cong 4 A, Y$	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	21	35	ns
Fall time ^c	t _f]		-	5	10	
Source-Drain Diode Ratings and Char	racteristics ^b						
Pulsed current ^a	I _{SM}			-	-	84	Α
Forward voltage	V _{SD}		= 8 A, V _{GS} = 0		0.82	1.2	V

Notes

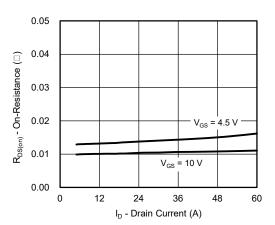
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

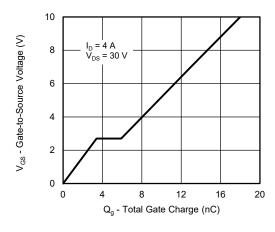




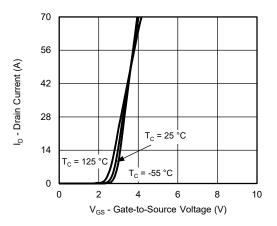
Output Characteristics



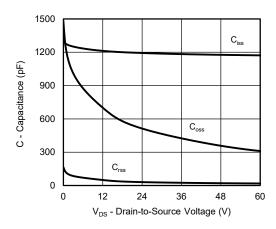
On-Resistance vs. Drain Current



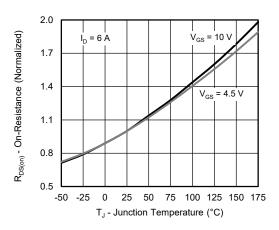
Gate Charge



Transfer Characteristics

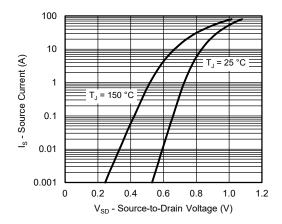


Capacitance

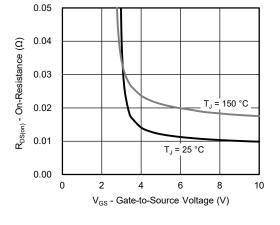


On-Resistance vs. Junction Temperature

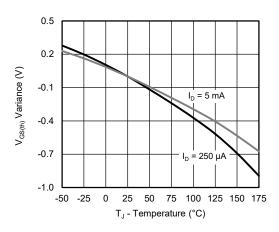




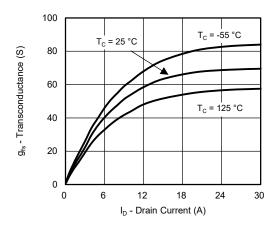
Source Drain Diode Forward Voltage



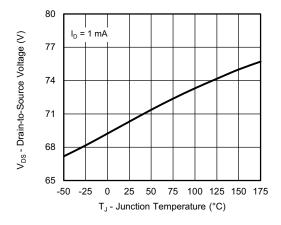
On-Resistance vs. Gate-to Source Voltage



Threshold Voltage

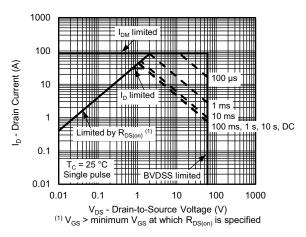


Transconductance

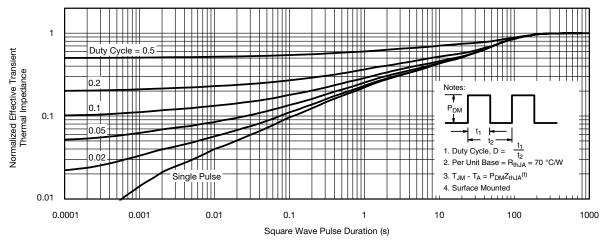


Drain Source Breakdown vs. Junction Temperature



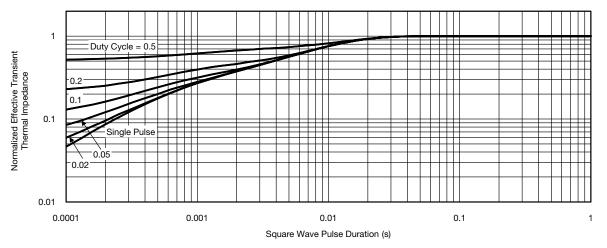


Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient





Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?75020.



PowerPAK® SO-8L Case Outline 2



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DIM		MILLIMETERS		INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	MIN. NOM.		
Α	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094		0.004			
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
E3	6.05	6.22	6.40	0.238	0.245	0.252	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51		0.020			
W	0.23			0.009			
W1		0.41			0.016		
W2	2.82		0.111				
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

DWG: 6044

Note

• Millimeters will govern



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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